A 2010 biography of and tribute to Professor Noriyuki Miyazaki by Sung Yi and Paul Conway in connection with the EMAP 2010 conference:

Dr. Noriyuki Miyazaki has been actively involved in EMAP since 2001. He was a Co-chair of 7th International Conference on Electronics Materials and Packaging (EMAP 2005).

Dr. Noriyuki Miyazaki is currently Professor of Mechanical Engineering and Science, Kyoto University Japan. He is a graduate of the University of Tokyo and received his B.Sc., M.Sc. and Ph.D. from the University of Tokyo. He was Research Scientist at Japan Atomic Energy Research Institute from 1977 to 1983 and was an associate professor of Chemical Engineering, Kyushu University from 1983 to 1996 and a professor of Chemical Engineering, Kyushu University before joining Kyoto University in 2005.

He received numerous awards and honors including JSME Award for Young Researchers in 1984, K. Washizu Medal at International Conference on Computational Engineering and Science, 2000, JSME Computational Mechanics Achievements Award, 2001, Best Paper Award at Japan Institute of Electronics Packaging) Best Paper Award, 2002, JSME Funai Award in 2004, JSME Computational Mechanics Award in 2005, JACM Computational Mechanics Award in 2007, APACM Computational Mechanics Award in 200, JSME Medal for Outstanding Paper in 2009, JIEP Best Paper Award in 2010. Also he served as a member of editorial board in numerous journals. He has published more than 240 refereed journal papers and 129 international conference papers.
Dr. Noriyuki Miyazaki will be sixty-two-years old on October 22. We would like to celebrate his sixty two-birthday at EMAP 2010. Our friend, Dr. Noriyuki Miyazaki, is not only distinguished scholar but also a truly wonderful person. We all wish him continued good health and many more productive years ahead.

**Selected Publications:**


Noriyuki Miyazaki, “Creep buckling analysis of circular cylindrical shell under both axial compression and internal or external pressure”, Computers & Structures, Vol. 28, No. 4, 1988, pp. 437-441


